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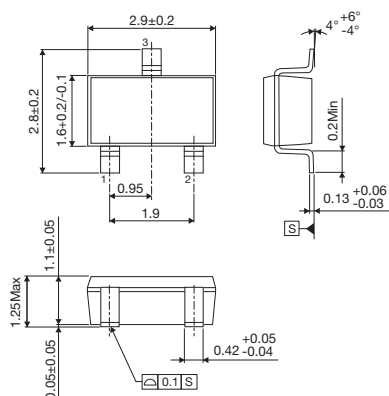
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Small封装

(单位: mm)

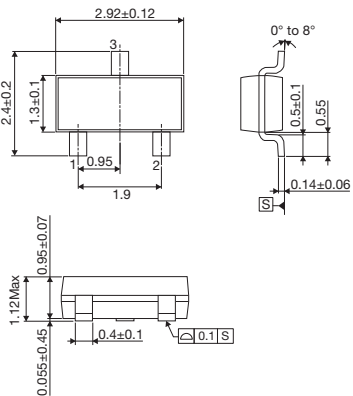
SOP封装

SSOP3



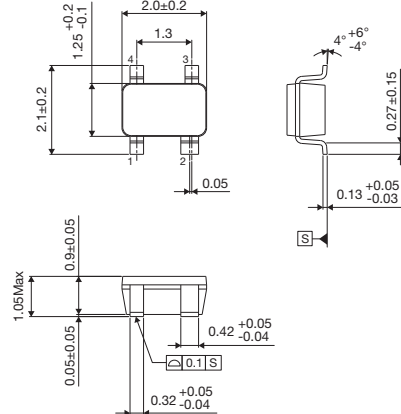
Taping: 3,000pcs

SSOP3A



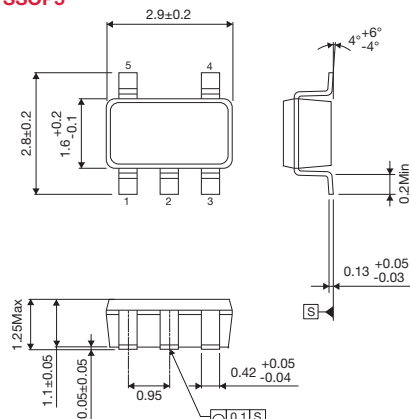
Taping: 3,000pcs

SOP4



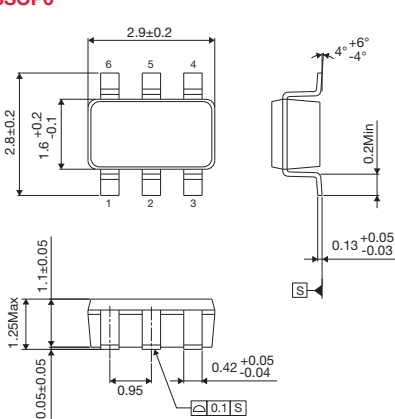
Taping: 3,000pcs

SSOP5



Taping: 3,000pcs

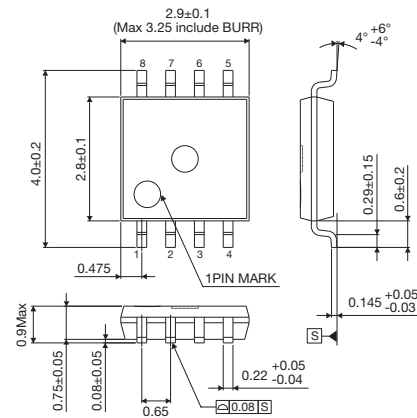
SSOP6



Taping: 3,000pcs

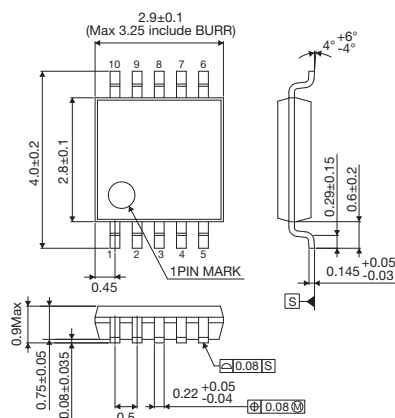
MSOP封装

MSOP8



Taping: 3,000pcs

MSOP10



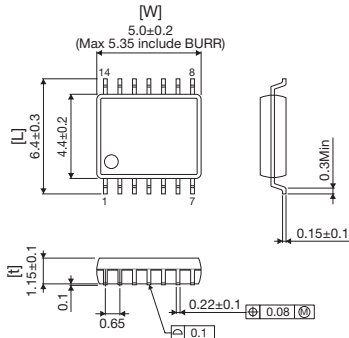
Taping: 3,000pcs

注: LAPIS Technology产品的封装请参照“LSI封装(LAPIS Technology产品)”。

SOP封装

(单位: mm)

SSOP Package (for SSOP-B14)



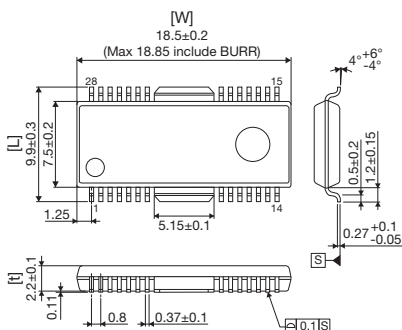
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	Package (pcs) taping
SOP Package Pin Pitch: 1.27mm	SOP8	8	6.2	5.0	1.61	2,500
	SOP-JW8		6.0	4.9	1.65	2,500
	SOP14	14	6.2	8.7	1.61	2,500
	SOP-J14		6.0	8.65	1.65	2,500
	SOP16	16	6.2	10.0	1.61	2,500
	SOP-J16A		6.0	9.9	1.55	2,500
	SOP18	18	7.8	11.2	1.91	2,000
	SOP20A	20	10.3	12.8	2.5	1,500
	SOP24	24	7.8	15.0	1.91	2,000
	SOP28	28	9.9	18.5	2.31	1,500
SSOP-A Package Pin Pitch: 0.8mm	SSOP-A16	16	6.2	6.6	1.61	2,500
	SSOP-A20	20	7.8	8.7	1.91	2,000
	SSOP-A24	24	7.8	10.0	1.9	2,000
	SSOP-A32	32	7.8	13.6	1.91	2,000
SSOP-B Package Pin Pitch: 0.65mm	SSOP-B8	8	6.4	3.0	1.25	2,500
	SSOP-B10W	10	10.2	3.5	1.9	1,500
	SSOP-B14	14	6.4	5.0	1.25	2,500
	SSOP-B16	16	6.4	5.0		2,500
	SSOP-B20	20	6.4	6.5		2,500
	SSOP-B20W		8.1	6.5	1.81	2,000
	SSOP-B24	24	7.6	7.8	1.25	2,000
	SSOP-B28	28	7.6	10.0		2,000
	SSOP-B28W		10.4	9.2	2.4	1,500
	SSOP-B40	40	7.8	13.6	1.9	2,000
TSSOP-B Package Pin Pitch: 0.65mm	TSSOP-B8	8	6.4	3.0	1.2	3,000
	TSSOP-B8J		4.9	3.0	1.1	2,500
	TSSOP-B14J	14	6.4	5.0	1.2	2,500
TSSOP-C Package Pin Pitch: 0.5mm	TSSOP-C48V	48	8.1	12.5	1.0	2,000

注: 尺寸详图请确认罗姆官网。

HSOP封装(双侧带散热片)

(单位: mm)

HSOP Package (for HSOP-M28)



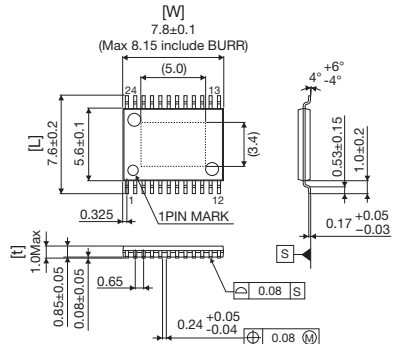
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	Package (pcs) taping
HSOP Package Pin Pitch: 1.27mm	HSOP20	20	7.8	14.9	2.1	2,000
HSOP Package Pin Pitch: 0.8mm	HSOP25	25	7.8	13.6	2.01	2,000
HSOP-M Package Pin Pitch: 0.8mm	HSOP-M28	28	9.9	18.5	2.31	1,500
	HSOP-M36	36	9.9	18.5	2.4	1,500

注: 尺寸详图请确认罗姆官网。

HTSOP封装(背面带散热片)

(单位: mm)

HTSSOP Package (for HTSSOP-B24)



	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	back heat sink (mm)	Package (pcs) taping
HTSOP Package Pin Pitch: 1.27mm	HTSOP-J8	8	6.0	4.9	1.0	2.4x3.2	2,500
	HTSOP-J8ES	8	6.0	4.9		1.8x2.2	2,500
HTSSOP-A Package Pin Pitch: 0.8mm	HTSSOP-A44	44	9.5	18.5	1.0	5.0x6.0	1,500
	HTSSOP-A44R		9.5	18.5		5.0x6.0 (surface)	1,500
HTSSOP-B Package Pin Pitch: 0.65mm	HTSSOP-B16	16	6.4	5.0	1.0	2.4x3.0	2,500
	HTSSOP-B20	20	6.4	6.5		2.4x4.0	2,500
	HTSSOP-B24	24	7.6	7.8		3.4x5.0	2,000
	HTSSOP-B28	28	6.4	9.7		2.9x5.5	2,500
	HTSSOP-B30	30	7.6	10.0		3.7x5.8	2,000
	HTSSOP-B40	40	7.8	13.6		3.4x8.4	2,000
	HTSSOP-B54	54	9.5	18.5		5.0x6.0	1,500
HTSSOP-C Package Pin Pitch: 0.5mm	HTSSOP-C48	48	8.1	12.5	1.0	4.2x5.0	2,000
	HTSSOP-C48R	48	8.1	12.5		4.2x5.0 (surface)	2,000
	HTSSOP-C64	64	8.1	17.2	1.1	3.05x4.45	2,000
HSSOP-C Package Pin Pitch: 0.5mm	HSSOP-C16	16	6.0	4.9	1.7	about 2.5x4.12	2,500

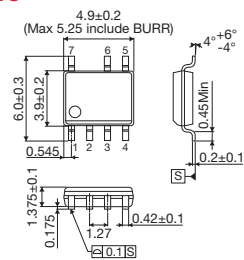
注: 尺寸详图请确认罗姆官网。

注: LAPIS Technology产品的封装请参照“LSI封装(LAPIS Technology产品)”。

SOP特殊封装

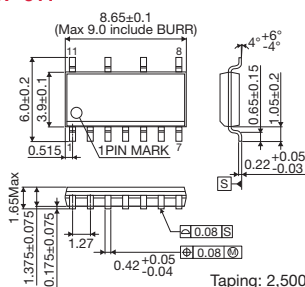
(单位: mm)

SOP-J7S



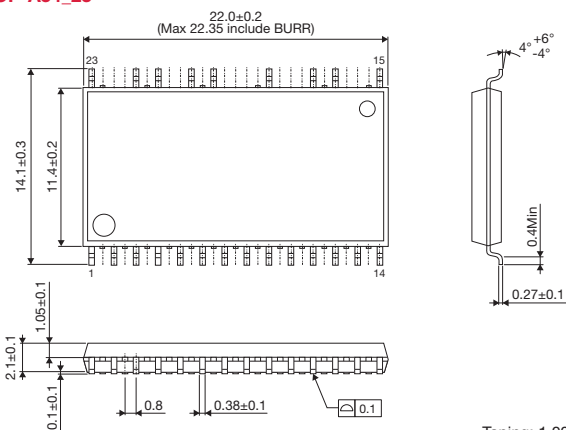
Taping: 2,500pcs

SOP-J11



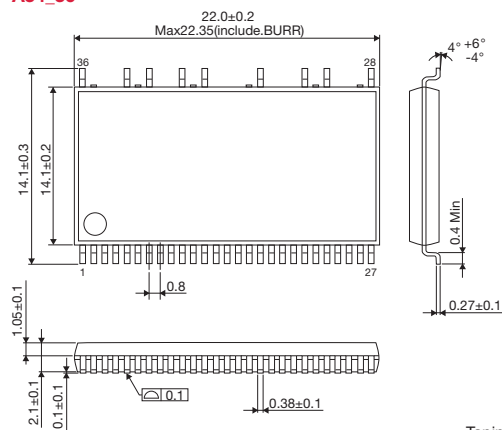
Taping: 2,500pcs

SSOP-A54_23



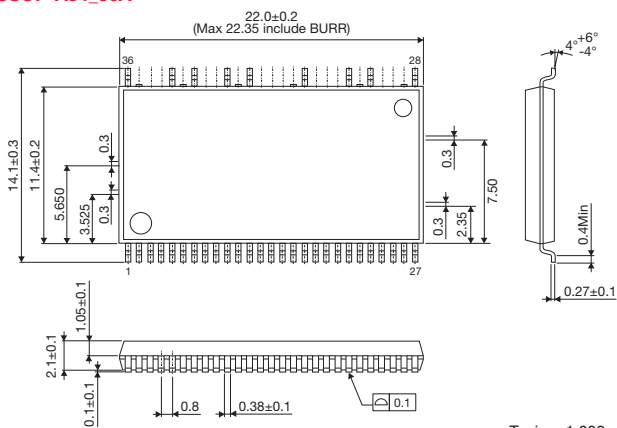
Taping: 1,000pcs

SSOP-A54_36



Taping: 1,000pcs

SSOP-A54_36A



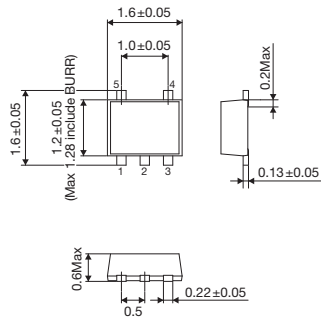
Taping: 1,000pcs

Non-lead封装

(单位: mm)

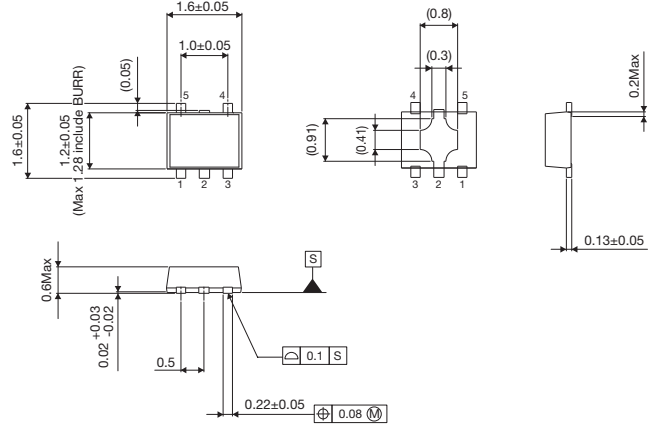
VSOF封装

VSOF5



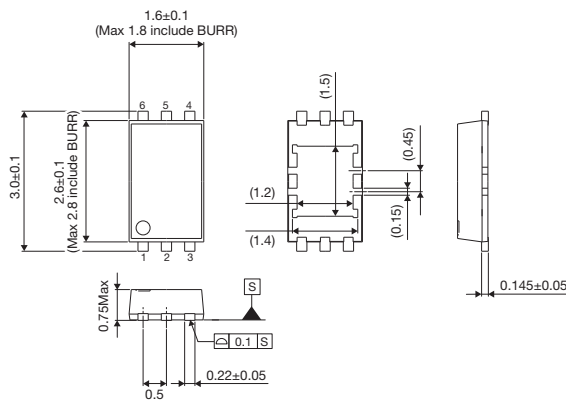
Taping: 3,000pcs

HVSOF5(With back heat sink)



Taping: 3,000pcs

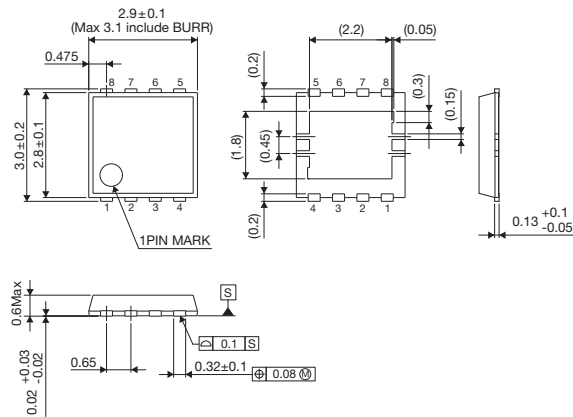
HVSOF6(With back heat sink)



Taping: 3,000pcs

HSO8封装(背面带散热片)

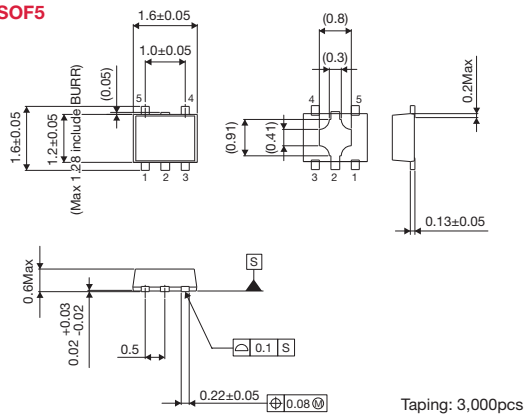
HSO8



Taping: 3,000pcs

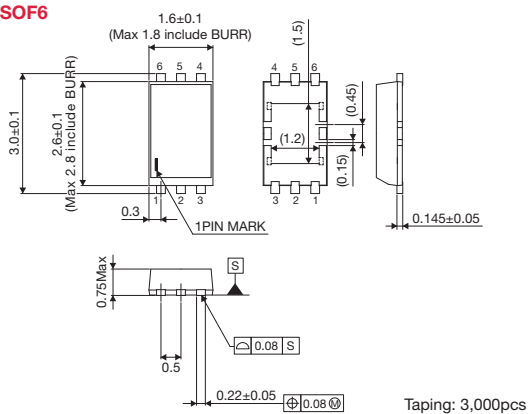
WSOF封装

WSOF5



Taping: 3,000pcs

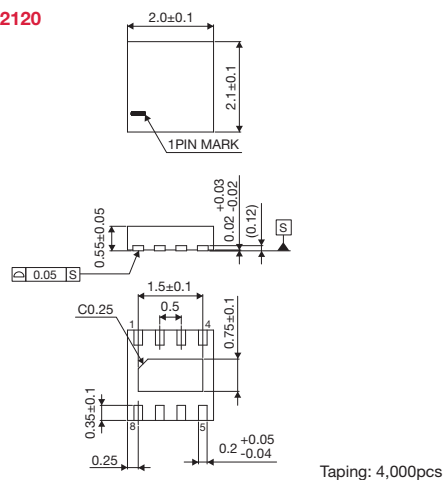
WSOF6



Taping: 3,000pcs

WSN封装

WS0N008X2120



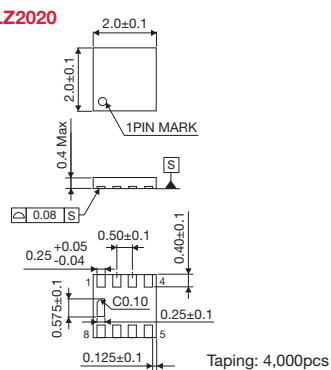
Taping: 4,000pcs

MMP封装

(単位: mm)

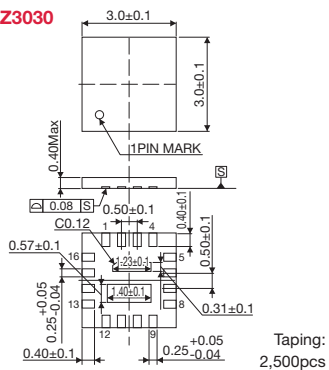
VMMP封装

VMMP08LZ2020



Taping: 4,000pcs

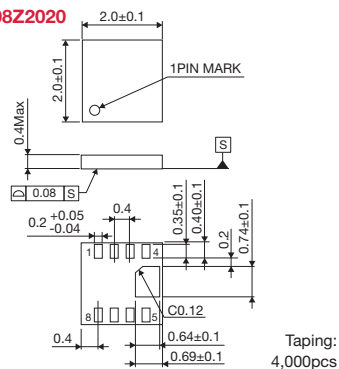
VMMP16LZ3030



Taping:
2,500pcs

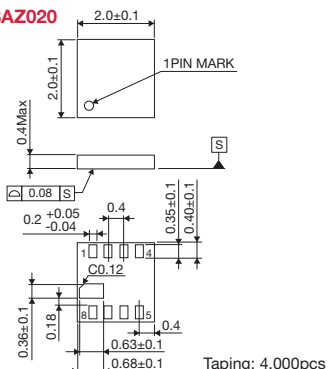
UMMP封装

UMMP008Z2020



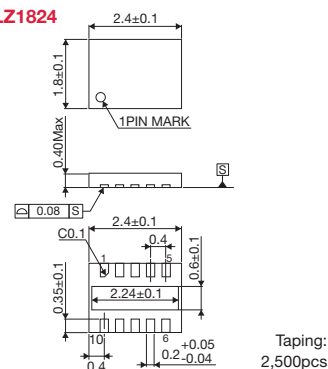
Taping:
4,000pcs

UMMP008AZ020



Taping: 4.000pcs

UMMP10LZ1824



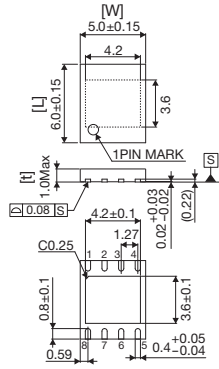
Taping:
2,500pcs

注：LAPIS Technology产品的封装请参照“LSI封装(LAPIS Technology产品)”。

SON封装(背面带散热片)

(单位: mm)

SON Package (for SON008V5060)



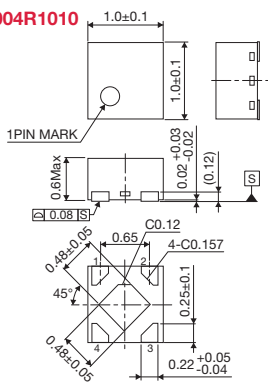
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	back heat sink (mm)	Package (pcs) taping
SON Package Pin Pitch: 1.27mm	SON008V5060	8	6.0	5.0	1.0	3.6×4.2	2,000
SSON Package Pin Pitch: 0.65mm	SSON004X1010	4	1.0	1.0	0.6	0.48×0.48	5,000
	SSON004X1216		1.6	1.2		0.8×0.75	5,000
USON Package Pin Pitch: 0.4mm	USON014X3020	14	2.0	3.0	0.6	0.8×2.5	4,000
	USON016X3315	16	1.5	3.3		0.6×2.9	4,000
VSON Package Pin Pitch: 0.5mm	VSON008V2030	8	3.0	2.0	0.6	1.4×1.5	3,000
	VSON008X2020		2.0	2.0		0.8×1.5	4,000
	VSON008X2030		3.0	2.0		1.4×1.5	4,000
	VSON08AX2030		3.0	2.0		1.4×1.5	4,000
	VSON010V3030	10	3.0	3.0	0.6	1.2×2.0	3,000
	VSON010X3020		2.0	3.0		0.64×2.0	4,000
	VSON010X3030		3.0	3.0		1.2×2.0	4,000
	VSON010V3030		3.0	3.0		1.2×2.0	3,000

注: 尺寸详图请确认罗姆官网。

SON特殊封装(背面带散热片)

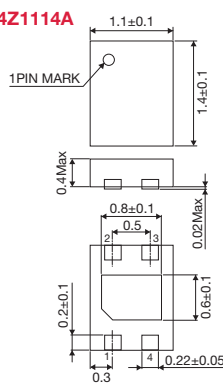
(单位: mm)

SSON004R1010



Taping: 5,000pcs

VSON04Z1114A

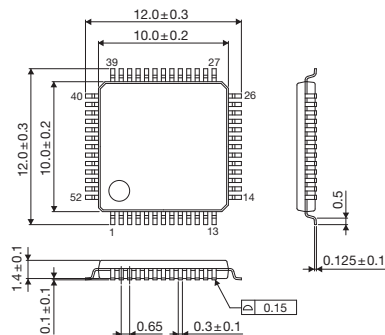


Taping: 5,000pcs

QFP封装

(单位: mm)

SQFP Package (for SQFP-T52)



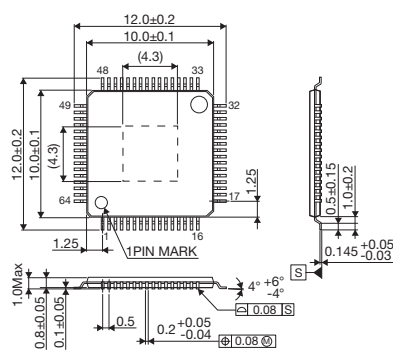
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	Package (pcs)	
SQFP-T Package Pin Pitch: 0.65mm	SQFP-T52	52	12.0	12.0	1.5	Tray	Taping
	SQFP-T64	64	14.0	14.0		1,000	1,000
	SQFP-T80C	80	16.0	16.0		1,000	—
TQFP Package Pin Pitch: 0.5mm	TQFP48V	48	9.0	9.0	1.2	500	—
	TQFP64V	64	12.0	12.0	1.1	1,000	1,500
	TQFP100V	100	16.0	16.0	1.2	1,000	1,000
VQFP Package Pin Pitch: 0.5mm	VQFP48C	48	9.0	9.0	1.6	500	500
	VQFP64	64	12.0	12.0		1,000	1,500
	VQFP80	80	14.0	14.0		1,000	1,000
	VQFP100	100	16.0	16.0		1,000	1,000

注: 尺寸详图请确认罗姆官网。

QFP封装(背面带散热片)

(单位: mm)

HTQFP Package (for HTQFP64AV)



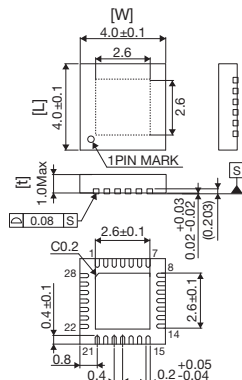
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	back heat sink (mm)	Package (pcs)	
HTQFP Package Pin Pitch: 0.5mm	HTQFP48V	48	9.0	9.0	1.0	4.4×4.4	Tray	Taping
	HTQFP64AV	64	12.0	12.0		4.3×4.3	—	1,500
	HTQFP64BV		12.0	12.0		6.5×6.5	—	1,000
HTQFP Package Pin Pitch: 0.4mm	HTQFP128UA	128	16.0	16.0	1.2	6.6×6.6	—	900
HQFP Package Pin Pitch: 0.5mm	HQFP144VM	144	22.0	22.0	1.6	6.0×6.0	—	60

注: 尺寸详图请确认罗姆官网。

QFN封装(背面带散热片)

(单位: mm)

UQFN Package (for UQFN28V4040A)



	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	back heat sink (mm)	Package (pcs) taping
SQFN Package Pin Pitch: 0.65mm	SQFN016V4040	16	4.0	4.0	1.0	2.1×2.1	2,500
UQFN Package Pin Pitch: 0.4mm	UQFN28V4040A	28	4.0	4.0	1.0	2.6×2.6	2,500
	UQFN036V5050	36	5.0	5.0		2.7×2.7	2,500
	UQFN040V5050	40	5.0	5.0		3.3×3.3	2,500
	UQFN056V7070	56	7.0	7.0		4.7×4.7	1,500
	UQFN56BV7070		7.0	7.0		4.0×4.0	1,500
	UQFN68CV8080	68	8.0	8.0		4.3×4.3	1,000
	UQFN88MV0100	88	10.0	10.0		7.8×7.8	1,000
VQFN Package Pin Pitch: 0.5mm	VQFN11X3535A	11	3.5	3.5	0.6	—	2,500
	VQFN016V3030	16	3.0	3.0	1.0	1.4×1.4	3,000
	VQFN16FV3030		3.0	3.0		1.4×1.4	3,000
	VQFN16KV3030		3.0	3.0		1.4×1.4	3,000
	VQFN16Z3030A	20	3.0	3.0	0.4	1.8×1.8	4,000
	VQFN20		4.2	4.2	0.95	—	2,500
	VQFN20FV3535		3.5	3.5	1.0	2.05×2.05	2,500
	VQFN20FV4040		4.0	4.0		2.1×2.1	2,500
	VQFN20PV3535		3.5	3.5		2.05×2.05	2,500
	VQFN20QV3535		3.5	3.5		2.05×2.05	2,500
	VQFN020V4040	24	4.0	4.0	1.0	2.1×2.1	2,500
	VQFN24FV4040		4.0	4.0		2.4×2.4	2,500
	VQFN24SV4040		4.0	4.0		2.4×2.4	2,500
	VQFN024V4040		4.0	4.0		2.4×2.4	2,500
	VQFN28FV5050	28	5.0	5.0	1.0	2.7×2.7	2,500
	VQFN28SV5050		5.0	5.0		2.7×2.7	2,500
	VQFN028V5050		5.0	5.0		2.7×2.7	2,500
	VQFN32FBV050		5.0	5.0		3.4×3.4	2,500
	VQFN32FAV050	32	5.0	5.0	1.0	3.4×3.4	2,500
	VQFN32SV5050		5.0	5.0		3.4×3.4	2,500
	VQFN032V5050		5.0	5.0		3.4×3.4	2,500
	VQFN36	36	6.2	6.2	0.95	—	2,500
	VQFN036V6060		6.0	6.0	1.0	3.6×3.6	2,000
	VQFN40W6060A	40	6.0	6.0	0.8	4.5×4.5	2,000
	VQFN040V6060		6.0	6.0	1.0	3.7×3.7	2,000
	VQFN40FV6060		6.0	6.0		4.4×4.4	2,000
	VQFN046V8080	46	8.0	8.0		6.1×3.85	1,000
	VQFN48V7070A	48	7.0	7.0	0.9	5.3×5.3	1,500
	VQFN48MCV070		7.0	7.0	1.0	5.6×5.6	1,500
	VQFN48FV7070		7.0	7.0		3.2×3.2	1,500
	VQFN048V7070		7.0	7.0		4.7×4.7	1,500
	VQFN56FCV080	56	8.0	8.0		4.5×4.5	1,000
	VQFN56AV8080		8.0	8.0		3.4×3.4	1,000
	VQFN56FV8080		8.0	8.0		5.5×5.5	1,000
WQFN Package Pin Pitch: 0.5mm	WQFN12X2520A	12	2.5	2.0	0.5	—	4,000

注: 尺寸详图请确认罗姆官网。

(单位: mm)

	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	Package (pcs) taping
SBGA Package Pin Pitch: 0.65mm	SBGA072T070A	72	7.0	7.0	1.2	1,500
VBGA Package Pin Pitch: 0.5mm	VBGA048W040	48	4.0	4.0	0.9	2,500
	VBGA049W040A	49	4.0	4.0	0.8	2,500
	VBGA064T050A	64	5.0	5.0	1.2	2,500
	VBGA099W060	99	6.0	6.0	0.9	2,000

注：尺寸详图请确认罗姆官网。

(单位: mm)

[illegible]

Taping: 2,500pcs

Figure 1: Dimensions of the PCB. The figure includes three views: Top View, Bottom View, and a side cross-section. The Top View shows a rectangular board with overall dimensions 2.8±0.1 inches by 2.8±0.1 inches (MOLD). It features a central square area with dimensions 2.65±0.1 inches by 2.65±0.1 inches (MOLD). The board has a thickness of 0.9±0.1 inches. The Bottom View shows a similar layout with dimensions 2.8±0.1 inches by 2.8±0.1 inches. It includes a central square area with dimensions 2.65±0.1 inches by 2.65±0.1 inches. The board has a thickness of 0.9±0.1 inches. The side cross-section shows a thickness of 0.9±0.1 inches and a 0.08 inch gap. The board is labeled 'Taping: 3,000pcs'.

1PIN MARK
HOLE (ø0.3)

2.0±0.1

0.5

0.5

2.0±0.1

1.0 Max

0.1x45°

3 4 5

6 7

8 9 10

(R0.1)

0.275±0.1

0.1

0.25±0.1

Taping: 3,000pcs

[illegible][illegible]

I C 封装

注：LAPIS Technology产品的封装请参照“LSI封装(LAPIS Technology产品)”。

WL-CSP封装

(单位: mm)

VCSP <引脚间距: 0.5mm>

VCSP85H	VCSP60N	VCSP50L	VCSP35L
2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs Embossed carrier tape: 3,000pcs

UCSP <引脚间距: 0.4mm>

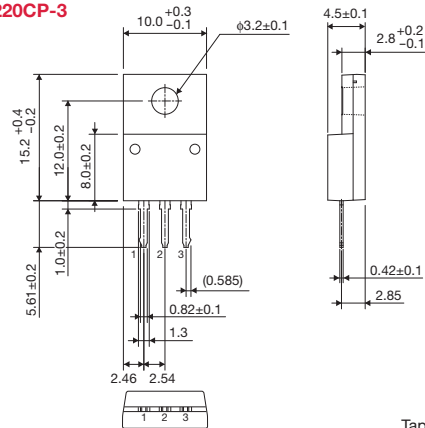
UCSP75M	UCSP55M	UCSP50L	UCSP35L
2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs	2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs Embossed carrier tape: 3,000pcs
UCSP30L	UCSP25L	UCSP16X	
2.8mm square size less than: 3,000pcs 2.81mm square size or more: 2,500pcs Embossed carrier tape: 3,000pcs	Embossed carrier tape: 3,000pcs	Embossed carrier tape: 3,000pcs	

Power封装

(单位: mm)

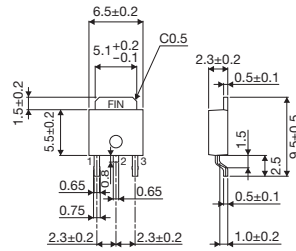
Power-3pin

TO220CP-3



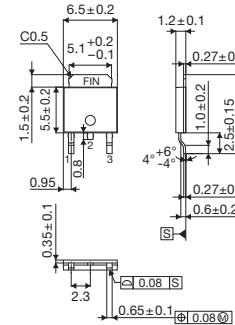
Taping: 500pcs

TO252-3



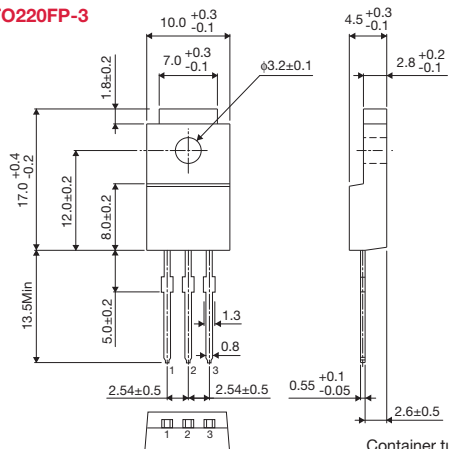
Taping: 2,000pcs

TO252S-3



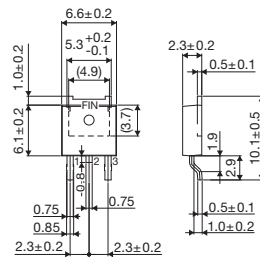
Taping: 2,000pcs

TO220FP-3



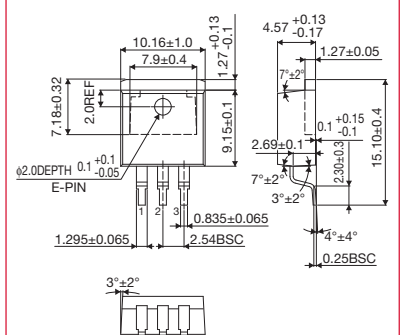
Container tube: 500pcs

TO252-J3



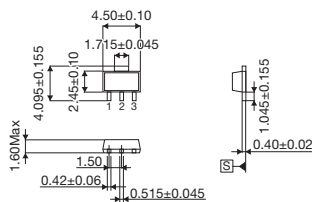
Taping: 2,000pcs

TO263-3



Taping: 500pcs

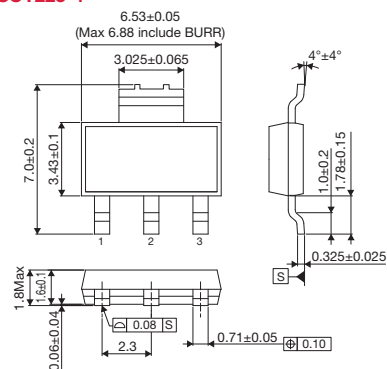
SOT89-3K



Taping: 1,000pcs

Power-4pin

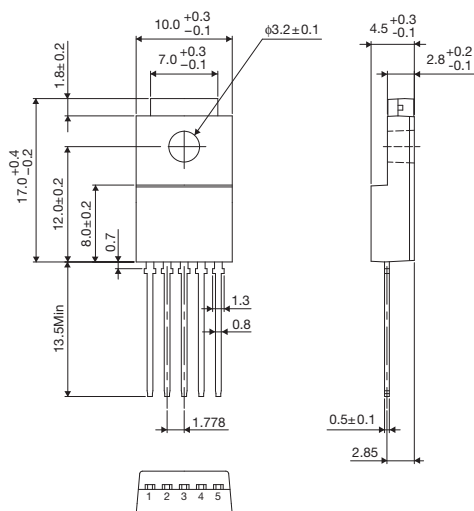
SOT223-4



Taping: 2,000pcs

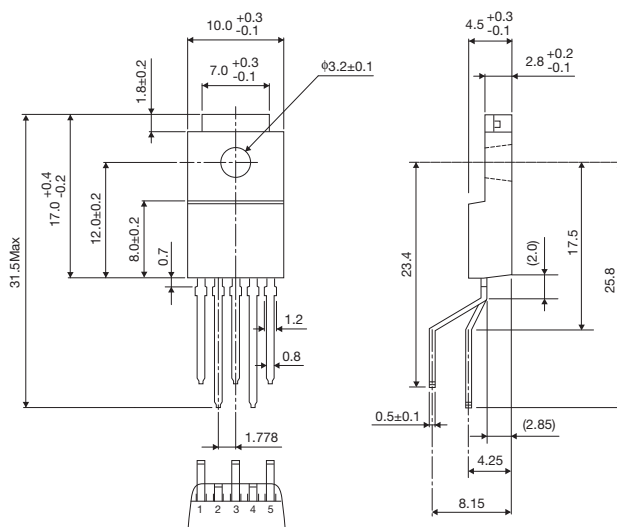
Power-5pin

TO220FP-5



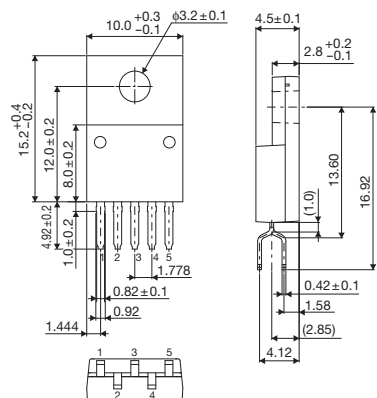
Tube: 500pcs

TO220FP-5 (V5)



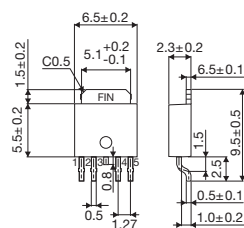
Tube: 500pcs

TO220CP-V5



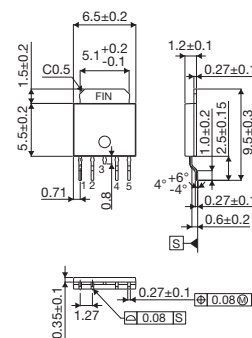
Taping: 500pcs

TO252-5



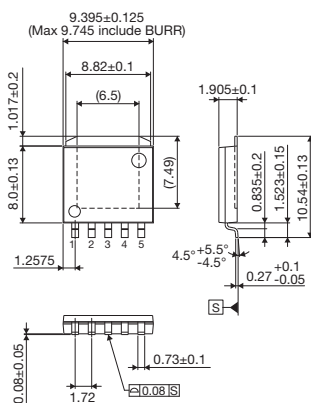
Taping: 2,000pcs

TO252S-5



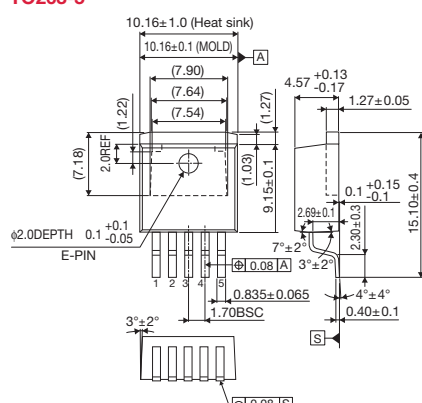
Taping: 2,000pcs

HRP5



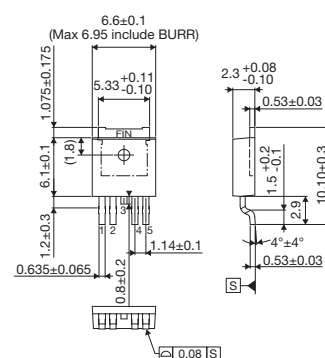
Taping: 2,000pcs

TO263-5



Taping: 500pcs

TO252-J5



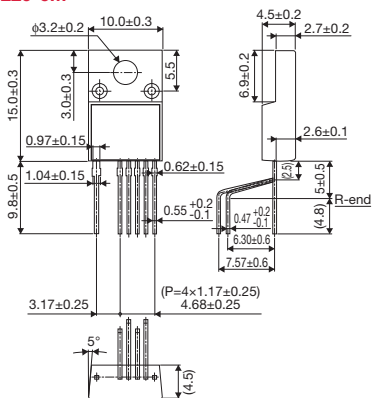
Taping: 2,000pcs

Power封装

(单位: mm)

Power-6pin

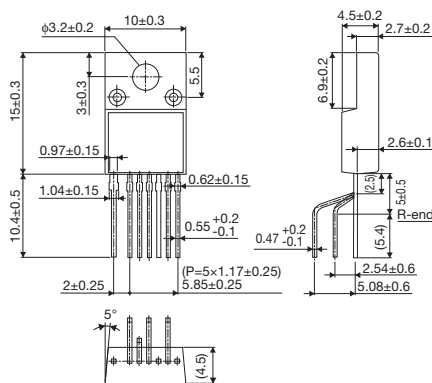
TO220-6M



Container tube: 238pcs

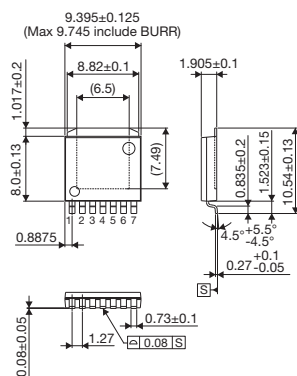
Power-7pin

TO220-7M



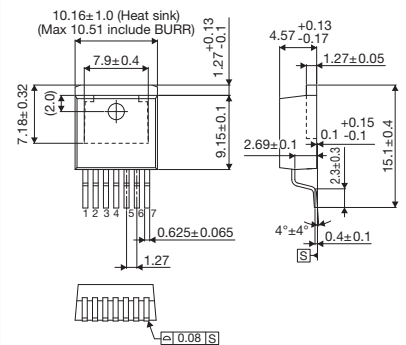
Container tube: 238pcs

HRP7



Taping: 2,000pcs

TO263-7



Taping: 2,000pcs

I C 封装

注：LAPIS Technology产品的封装请参照“LSI封装(LAPIS Technology产品)”。

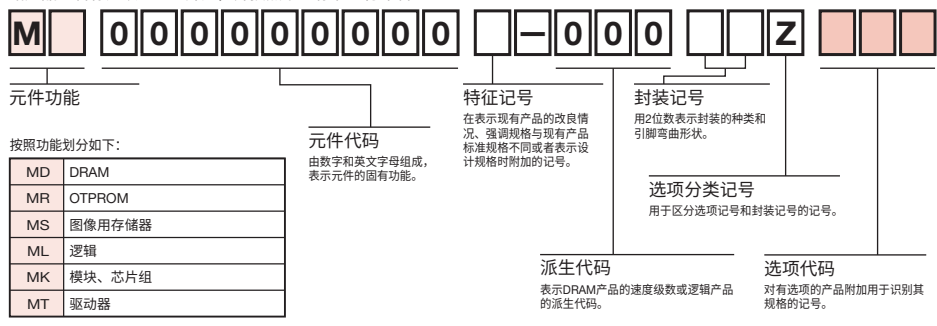
LAPIS Technology封装

品名构成说明	P.122	WSON封装	P.126
SOP封装	P.122	BGA封装	P.126
QFP封装	P.123	WL-CSP封装	P.127
QFN封装	P.124		

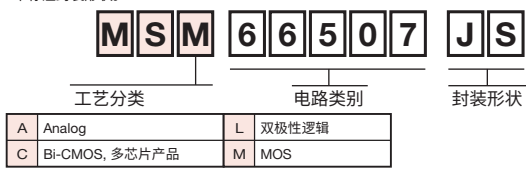
刊载各封装的代表性外形图。详细内容请咨询销售人员。

品名构成说明

半导体集成电路产品的名称是以“M”开头，并按照下述标准进行命名。

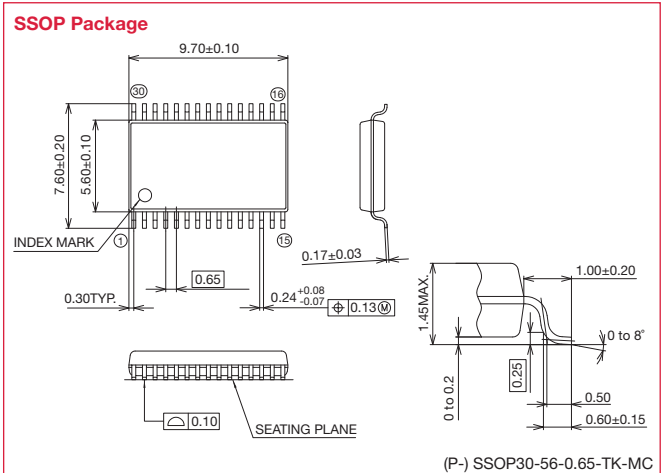


以往产品的标注方式如下所示。
· 不标注封装形状。



SOP封装

(单位: mm)



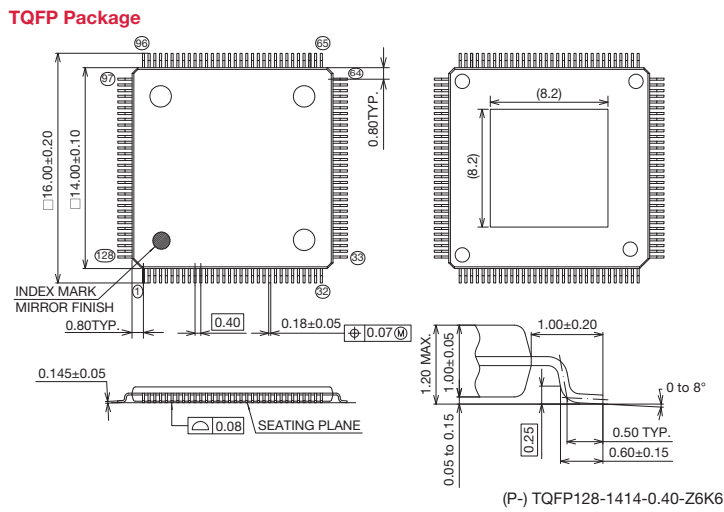
	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	TRAY (pcs)	T&R (pcs)
SSOP Package Pin Pitch: 1mm	SSOP32-430-1.00-XXX	32	12.0	15.95	2.50	1,280	1,000
SSOP Package Pin Pitch: 0.65mm	(P-) SSOP16-0225-0.65-XXX	16	6.4	5.0	1.15	4,760	2,500
	(P-) SSOP30-56-0.65-XXX	30	7.6	9.7	1.45	2,000	2,000
		30	7.6	9.7	1.85	2,000	2,000
TSSOP Package Pin Pitch: 0.65mm	(P-) TSSOP20-0225-0.65-XXX	20	6.4	6.5	1.10	4,160	2,000
VSSOP Package Pin Pitch: 0.65mm	P-VSSOP8-0150-0.65-XXX	8	4.0	2.9	0.90	—	3,000

注1: 尺寸详图请确认罗姆官网。
注2: 封装的后缀“-XXX”中加入选项代码。根据不同的制造网点及内部结构等分配代码。详细内容请咨询销售人员。

刊载各封装的代表性外形图。详细内容请咨询销售人员。

QFP封装

(单位: mm)



QFP

	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	TRAY (pcs)	T&R (pcs)
QFP Package Pin Pitch: 0.8mm	QFP44-P-910-0.80-XXX	44	13.5	14.5	2.25	1,440	1,000
	(P-) QFP64-1414-0.80-XXX	64	17.2	17.2	2.80	840	—
	(P-) QFP80-1420-0.80-XXX	80	19.0	25.0	2.50	600	—
QFP Package Pin Pitch: 0.65mm	(P-) QFP56-910-0.65-XXX	56	13.5	14.5	2.25	1,400	1,000
	(P-) QFP80-1414-0.65-XXX	80	17.2	17.2	3.05	840	—
	(P-) QFP100-1420-0.65-XXX	100	19.0	25.0	2.50	600	—

注1: 尺寸详图请确认罗姆官网。

注2: 封装的后缀“-XXX”中加入选项代码。根据不同的制造网点及内部结构等分配代码。详细内容请咨询销售人员。

LQFP

	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	TRAY (pcs)	T&R (pcs)
LQFP Package Pin Pitch: 0.8mm	(P-) LQFP32-0707-0.80-XXX	80	9.0	9.0	1.600	2,500	1,000
LQFP Package Pin Pitch: 0.50mm	(P-) LQFP144-2020-0.50-XXX	50	22.0	22.0	1.600	600	—

注1: 尺寸详图请确认罗姆官网。

注2: 封装的后缀“-XXX”中加入选项代码。根据不同的制造网点及内部结构等分配代码。详细内容请咨询销售人员。

TQFP

	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	TRAY (pcs)	T&R (pcs)
TQFP Package Pin Pitch: 0.80mm	(P-) TQFP32-0707-0.80-XXX	32	9.0	9.0	1.20	2,500	1,000
	(P-) TQFP44-1010-0.80-XXX	44	12.0	12.0	1.20	1,600	1,000
TQFP Package Pin Pitch: 0.65mm	(P-) TQFP52-1010-0.65-XXX	52	12.0	12.0	1.20	1,600	1,000
TQFP Package Pin Pitch: 0.5mm	(P-) TQFP48-0707-0.50-XXX	48	9.0	9.0	1.20	2,500	1,000
	(P-) TQFP64-1010-0.50-XXX	64	12.0	12.0	1.20	1,600	1,000

注1: 尺寸详图请确认罗姆官网。

注2: 封装的后缀“-XXX”中加入选项代码。根据不同的制造网点及内部结构等分配代码。详细内容请咨询销售人员。

刊载各封装的代表性外形图。详细内容请咨询销售人员。

QFP封装

(单位: mm)

TQFP

	Package	Pin Number (pin)	Length [L] (mm)	Width [W] (mm)	Thickness [t] (mm)	TRAY (pcs)	T&R (pcs)
TQFP Package Pin Pitch: 0.5mm	(P-) TQFP80-1212-0.50-XXX	80	14.0	14.0	1.20	1,190	—
	(P-) TQFP100-1414-0.50-XXX	100	16.0	16.0	1.20	900	—
TQFP Package Pin Pitch: 0.40mm	(P-) TQFP80-1010-0.40-XXX	80	12.0	12.0	1.20	1,600	—
	(P-) TQFP120-1414-0.40-XXX	120	16.0	16.0	1.20	900	—
	(P-) TQFP128-1414-0.40-XXX	128	16.0	16.0	1.20	900	—

注1: 尺寸详图请确认罗姆官网。

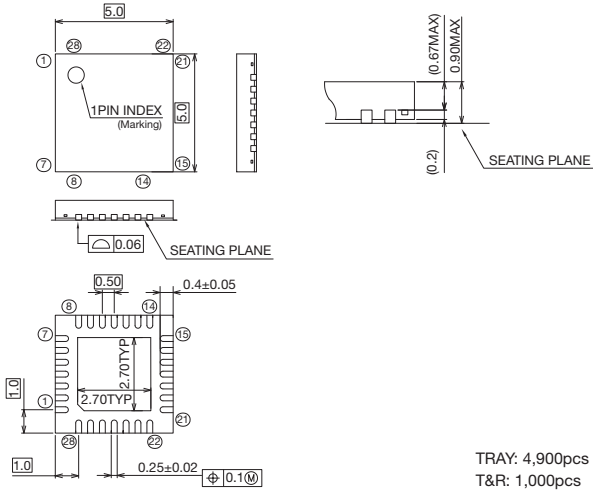
注2: 封装的后缀“XXX”中加入选项代码。根据不同的制造网点及内部结构等分配代码。详细内容请咨询销售人员。

QFN封装

(单位: mm)

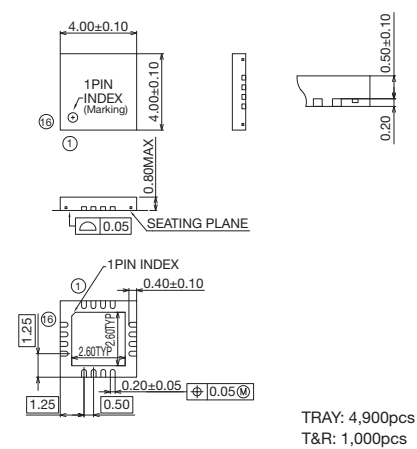
VQFN

P-VQFN28-0505-0.50-U66

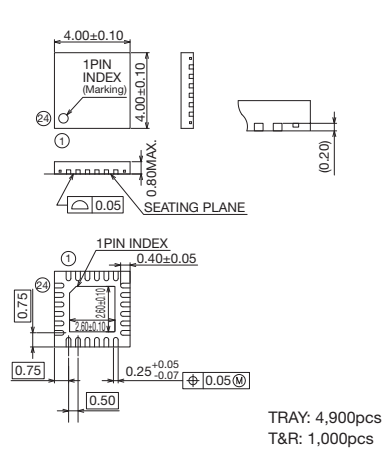


WQFN

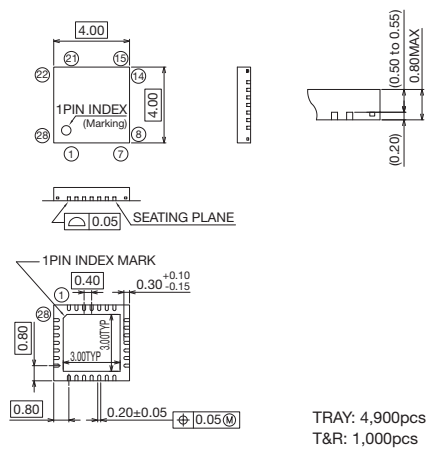
P-WQFN16-0404-0.50-63



P-WQFN24-0404-0.50-A63



P-WQFN28-0404-0.40-63



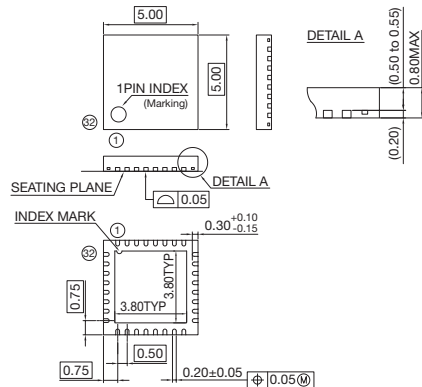
刊载各封装的代表性外形图。详细内容请咨询销售人员。

QFN封装

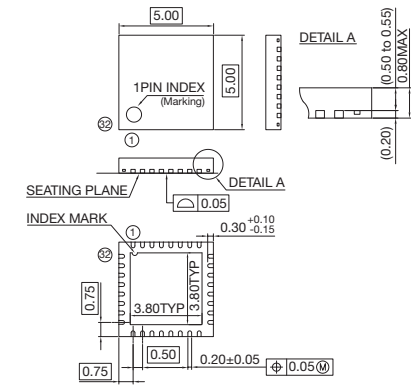
(单位: mm)

WQFN

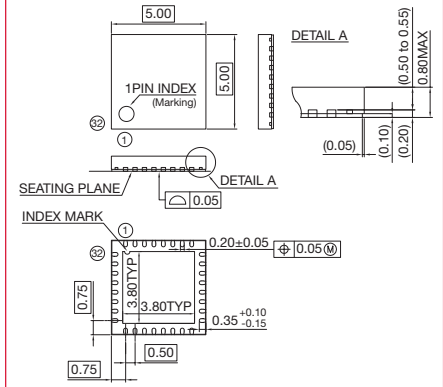
P-WQFN32-0505-0.50-A63

TRAY: 4,030pcs
T&R: 1,000pcs

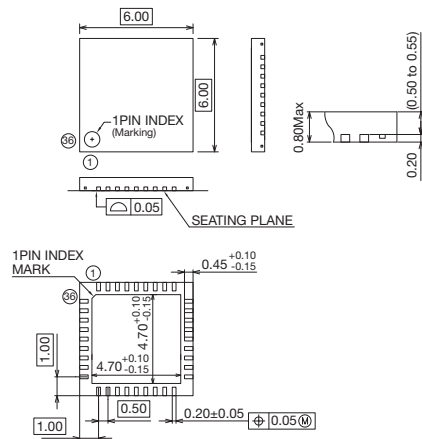
P-WQFN32-0505-0.50-A63-MC

TRAY: 403pcs
T&R: 1,000pcs

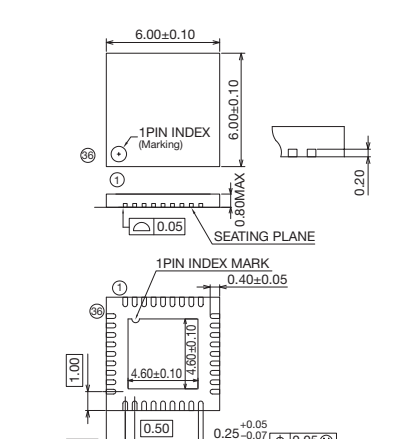
P-WQFN32-0505-0.50-W66

TRAY: 4,030pcs
T&R: 1,000pcs

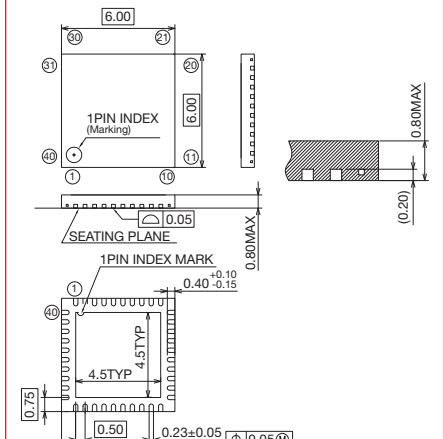
WQFN36-0606-0.50-A63

TRAY: 4,900pcs
T&R: 2,000pcs

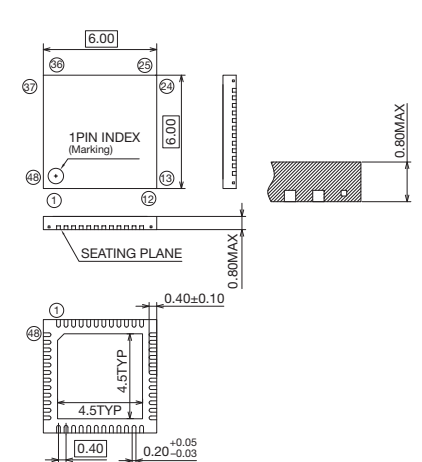
P-WQFN36-0606-0.50-T63

TRAY: 490pcs
T&R: 2,000pcs

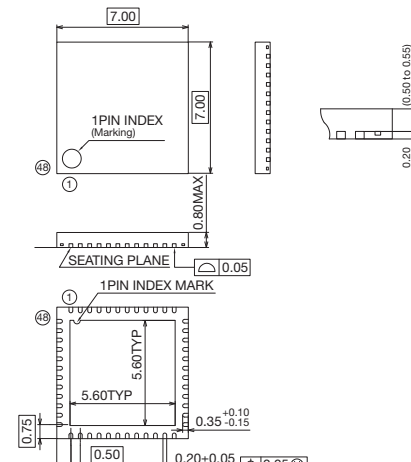
P-WQFN40-0606-0.50-63

TRAY: 4,900pcs
T&R: 2,500pcs

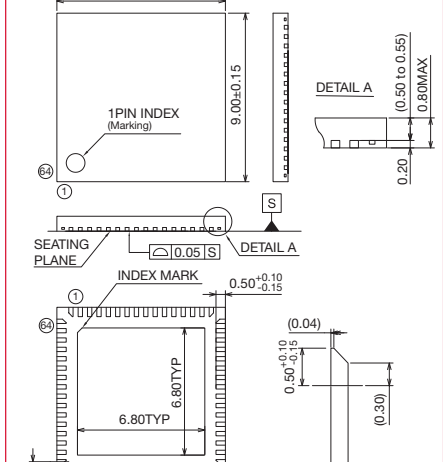
P-WQFN48-0606-0.40-T63-MC

TRAY: —
T&R: 3,000pcs

P-WQFN48-0707-0.50-63

TRAY: 2,500pcs
T&R: 2,000pcs

P-WQFN64-0909-0.50-63

TRAY: 2,600pcs
T&R: 3,000pcs

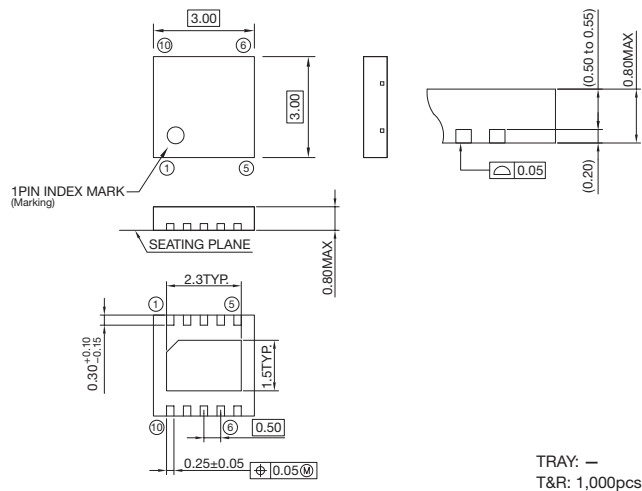
刊载各封装的代表性外形图。详细内容请咨询销售人员。

WSN封装

(单位: mm)

WSON

P-WSN10-0303-0.50-63



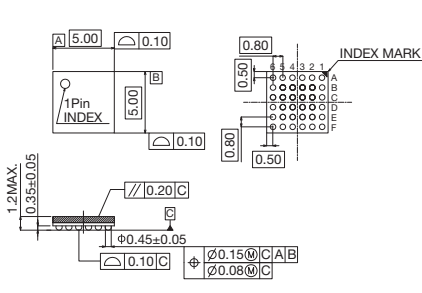
TRAY: —
T&R: 1,000pcs

BGA封装

(单位: mm)

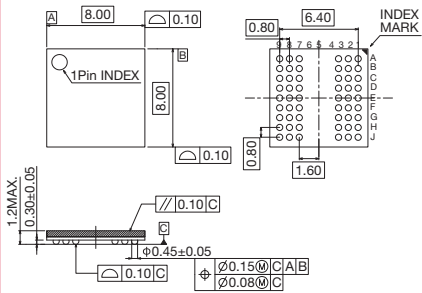
TFBGA

P-TFBGA36-0505-0.80-9



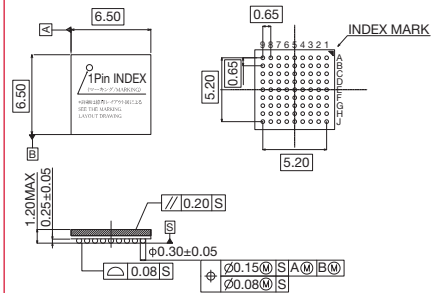
TRAY: 3,770pcs
T&R: —

P-TFBGA54-0808-0.80-9



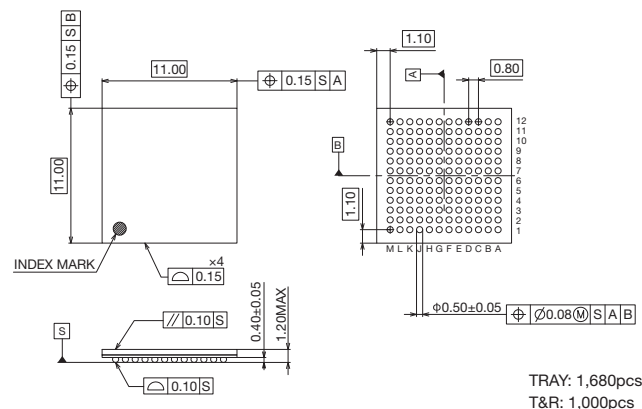
TRAY: 3,480pcs
T&R: 2,000pcs

P-TFBGA81-6.5×6.5-0.65-9-MC



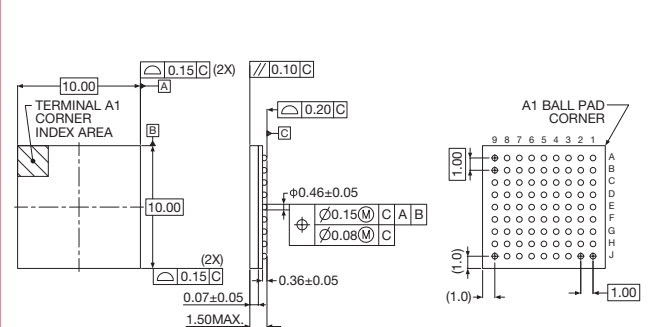
TRAY: —
T&R: 2,000pcs

P-TFBGA144-1111-0.80-1



TRAY: 1,680pcs
T&R: 1,000pcs

P-LBGA81-1010-1.00-1-MC



TRAY: 1,680pcs
T&R: —

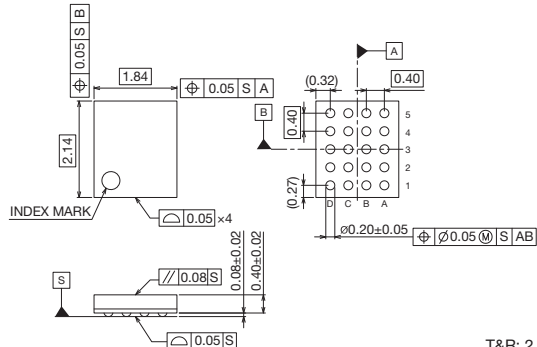
刊载各封装的代表性外形图。详细内容请咨询销售人员。

WL-CSP封装

(单位: mm)

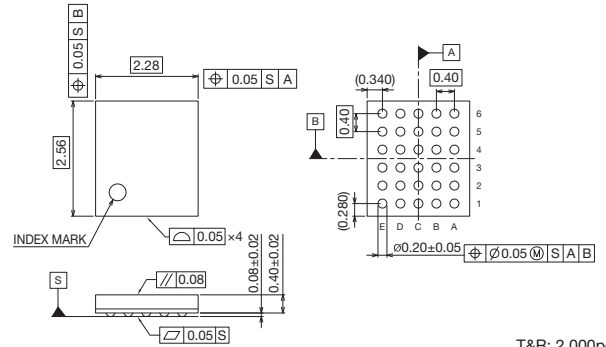
WCSP

S-UFLGA20-1.84×2.14-0.40-W



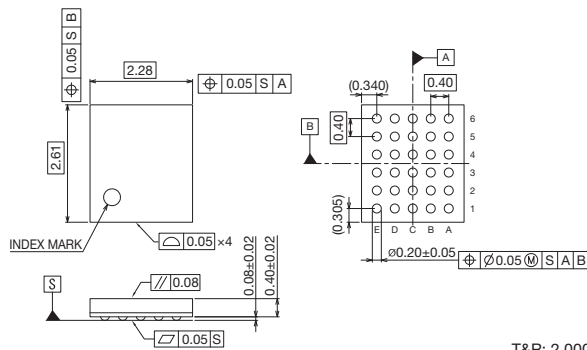
T&R: 2,000pcs

S-UFLGA30-2.28×2.56-0.40-W



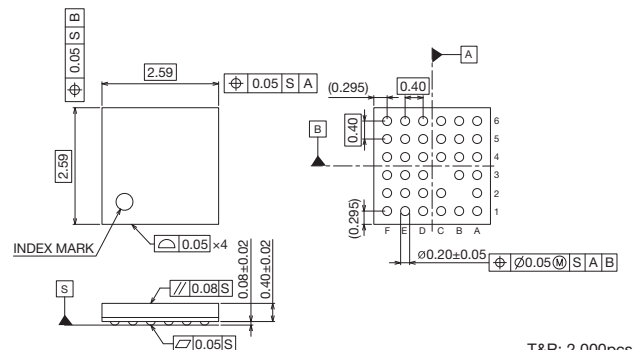
T&R: 2,000pcs

S-UFLGA30-2.28×2.61-0.40-W



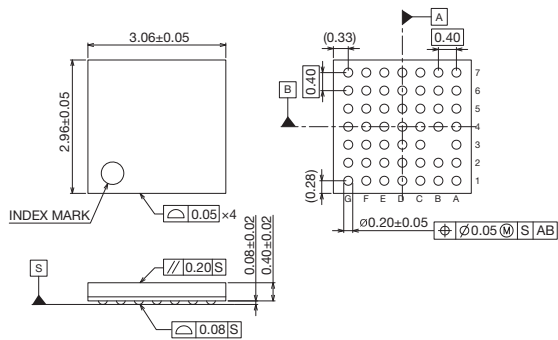
T&R: 2,000pcs

S-UFLGA34-2.59×2.59-0.40-W



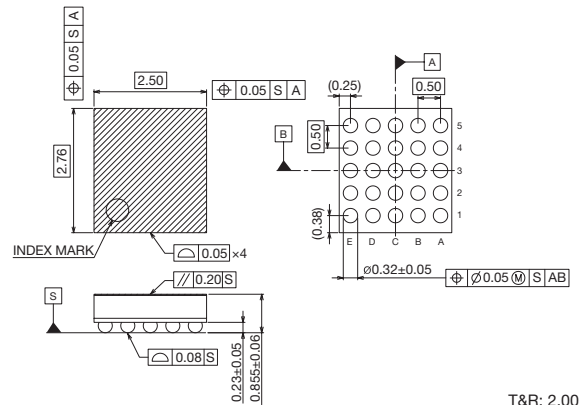
T&R: 2,000pcs

S-UFLGA48-3.06×2.96-0.40-W



T&R: 2,000pcs

S-VFBGA25-2.76×2.50-0.50-W



T&R: 2,000pcs